

## 5-V Dual TTL-to-Differential PECL Translator

### FEATURES

- 1.1-ns (max) Propagation Delay
- Operating Range:  $V_{CC} = 4.2V$  to  $5.7V$  with  $GND = 0 V$
- < 50-ps (typ) Output-to-Output Skew
- Built-In Temperature Compensation
- Drop-In Compatible to the MC10ELT22, MC100ELT22

### APPLICATIONS

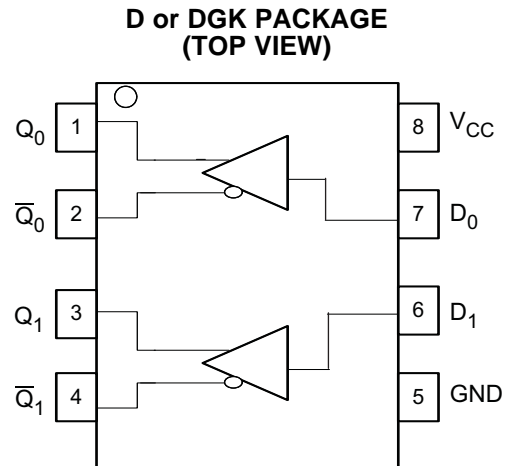
- Data and Clock Transmission Over Backplane
- Signaling Level Conversion for Clock or Data

### DESCRIPTION

The SN65ELT22 is a dual TTL-to-differential PECL translator. It operates on +5-V supply and ground only. The output is undetermined when the inputs are left floating. The low output skew makes the device an ideal solution for clock or data signal translation.

The SN65ELT22 is housed in an industry standard SOIC-8 package and is also available in an optional TSSOP-8 package.

### PIN ASSIGNMENT



**Table 1. Pin Descriptions**

PIN	FUNCTION
$D_0, D_1$	TTL inputs
$Q_0, \bar{Q}_0, Q_1, \bar{Q}_1$	PECL outputs
$V_{CC}$	Positive supply
GND	Ground

### ORDERING INFORMATION<sup>(1)</sup>

PART NUMBER	PART MARKING	PACKAGE	LEAD FINISH
SN65ELT22D	SN65ELT22	SOIC	NiPdAu
SN65ELT22DGK	SN65ELT22	SOIC-TSSOP	NiPdAu

(1) Leaded device options are not initially available; contact a sales representative for further details



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

PARAMETER	CONDITIONS	VALUE	UNIT
Absolute PECL mode supply voltage, $V_{CC}$	GND = 0 V	6	V
Input voltage, $V_{IN}$	GND = 0 V	$GND + 0.025 < V_{IN} < V_{CC} - 0.025$	V
Output current	Continuous	50	mA
	Surge	100	
Operating temperature range		–40 to 85	°C
Storage temperature range		–65 to 150	°C

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## POWER DISSIPATION RATINGS

PACKAGE	CIRCUIT BOARD MODEL	POWER RATING $T_A < 25^\circ\text{C}$ (mW)	THERMAL RESISTANCE, JUNCTION-TO-AMBIENT NO AIRFLOW	DERATING FACTOR $T_A > 25^\circ\text{C}$ (mW/°C)	POWER RATING $T_A = 85^\circ\text{C}$ (mW)
SOIC	Low-K	719	139	7	288
	High-K	840	119	8	336
SOIC-TSSOP	Low-K	469	213	5	188
	High-K	527	189	5	211

## THERMAL CHARACTERISTICS

PARAMETER		MIN	TYP	MAX	UNIT
$\theta_{JB}$	Junction-to-board thermal resistance	SOIC	79		°C/W
		SOIC-TSSOP	120		
$\theta_{JC}$	Junction-to-case thermal resistance	SOIC	98		°C/W
		SOIC-TSSOP	74		

## KEY ATTRIBUTES

CHARACTERISTICS	VALUE	
Moisture sensitivity level	Level 1	
Flammability rating (oxygen index: 28 to 34)	UL 94 V-0 at 0.125 in	
Electrostatic discharge	Human body model	4 kV
	Charge device model	2 kV
	Machine model	200 V
Meets or exceeds JEDEC Spec EIA/JESD78 latchup test		

## PECL DC CHARACTERISTICS

At  $V_{CC} = 5.0\text{ V}$ ,  $GND = 0.0\text{ V}$  (unless otherwise noted)<sup>(1)(2)</sup>

PARAMETER	TEST CONDITIONS	$T_A = -40^\circ\text{C}$			$T_A = 25^\circ\text{C}$			$T_A = 85^\circ\text{C}$			UNIT	
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX		
$I_{CC}$	Power supply current		17.3	20		18.2	20		19.4	22	mA	
$V_{OH}$	High-level output voltage	See <sup>(3)</sup>	3915	3954	4120	3915	3958	4120	3915	3961	4120	mV
$V_{OL}$	Low-level output voltage	See <sup>(3)</sup>	3170	3236	3380	3170	3231	3380	3170	3229	3380	mV

- (1) The device meets the specifications after thermal balance has been established when mounted in a socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
- (2) Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{CC}$  can vary  $+0.7\text{ V}/-0.8\text{ V}$ .
- (3) Outputs are terminated through a 50- $\Omega$  resistor to  $V_{CC} - 2.0\text{ V}$ .

## TTL DC CHARACTERISTICS

At  $V_{CC} = 4.2\text{ V}$  to  $5.7\text{ V}$ ,  $T_A = -40^\circ\text{C}$  to  $85^\circ\text{C}$  (unless otherwise noted)<sup>(1)</sup>

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$I_{IH}$	High-level input current $V_{IN} = 2.7\text{ V}$ , $V_{IN} = (V_{CC} - 0.025)\text{ V}$			20	$\mu\text{A}$
$I_{IHH}$	High-level input current $V_{IN} = V_{CC}$			20	$\mu\text{A}$
$I_{IL}$	Low-level input current $V_{IN} = 0.5\text{ V}$ , $V_{IN} = (GND + 0.025)\text{ V}$			-200	$\mu\text{A}$
$V_{IK}$	Input clamp diode voltage $I_{IN} = -18\text{ mA}$			-1.2	V
$V_{IH}$	High-level input voltage	2.0	$V_{CC} - 0.025$		V
$V_{IL}$	Low-level input voltage	$GND + 0.025$		0.8	V

- (1) The device meets the specifications after thermal balance has been established when mounted in a socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

## AC CHARACTERISTICS

At  $V_{CC} = 4.2\text{ V}$  to  $5.7\text{ V}$ ,  $GND = 0.0\text{ V}$  (unless otherwise noted)<sup>(1)</sup>

PARAMETER	TEST CONDITIONS	$T_A = -40^\circ\text{C}$			$T_A = 25^\circ\text{C}$			$T_A = 85^\circ\text{C}$			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	
$f_{MAX}$	Max switching frequency <sup>(2)</sup> , see Figure 5		500			490			470		MHz
$t_{PLH}$	Propagation delay time 1.5 V to 50%	0.6	0.83	1.1	0.6	0.84	1.1	0.6	0.85	1.1	ns
$t_{PHL}$		0.5		0.9	0.5		0.9	0.5		0.9	
$t_{SKEW}$	Within device skew	See <sup>(3)</sup>	25	90	25	90	25	90	25	90	ps
	Device-to-device skew	See <sup>(4)</sup>	25	100	25	100	25	100	25	100	
$t_{JITTER}$	Random clock jitter (RMS)			0.5		0.5			0.5		ps
$t_r/t_f$	Output rise/fall times	Q (20%–80%)	0.7	1.1	0.7	1.1	0.7	1.1	0.7	1.1	ns

- (1) The device meets the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are assured only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.
- (2) Maximum switching frequency measured at output amplitude of 300 mV<sub>pp</sub>.
- (3) Measured between outputs under the identical transitions and conditions on any one device.
- (4) Device-to-device skew for identical transitions at identical  $V_{CC}$  levels.

Typical Termination for Output Driver

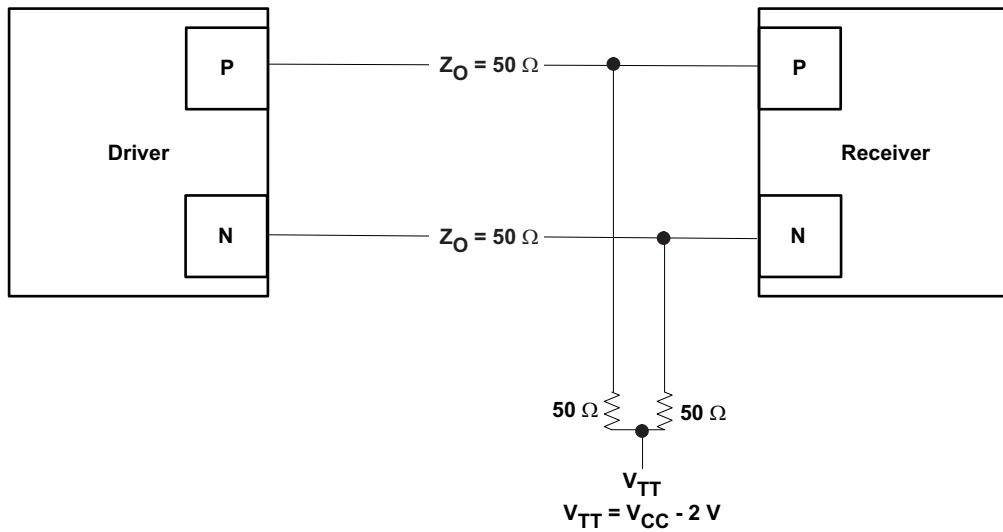


Figure 1. Typical Termination for Driver

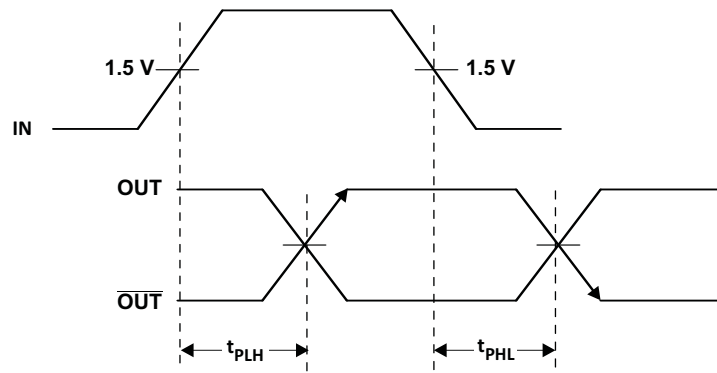


Figure 2. Output Propagation Delay



Figure 3. Output Rise and Fall Times

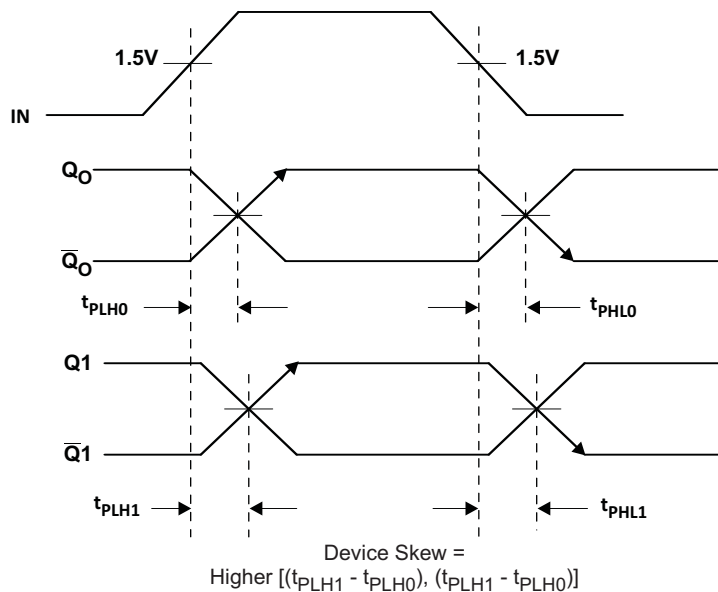


Figure 4. Device Skew

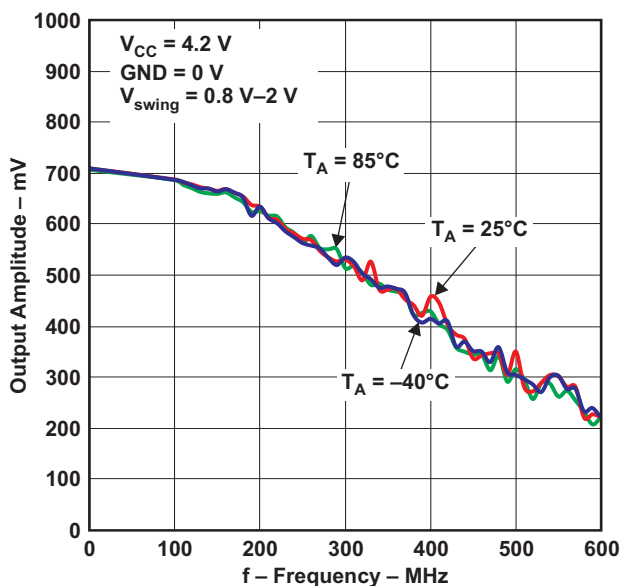


Figure 5. Output Amplitude vs. Frequency

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65ELT22D	ACTIVE	SOIC	D	8	75	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ELT22	<a href="#">Samples</a>
SN65ELT22DGK	ACTIVE	VSSOP	DGK	8	80	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SIPI	<a href="#">Samples</a>
SN65ELT22DGKR	ACTIVE	VSSOP	DGK	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	SIPI	<a href="#">Samples</a>
SN65ELT22DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ELT22	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) **MSL, Peak Temp.** - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) **Lead finish/Ball material** - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65ELT22DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
SN65ELT22DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65ELT22DGKR	VSSOP	DGK	8	2500	356.0	356.0	35.0
SN65ELT22DR	SOIC	D	8	2500	356.0	356.0	35.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN65ELT22D	D	SOIC	8	75	506.6	8	3940	4.32
SN65ELT22DGK	DGK	VSSOP	8	80	330.2	6.6	3005	1.88



D0008A

# PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

- Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- This dimension does not include interlead flash.
- Reference JEDEC registration MS-012, variation AA.

# EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# DGK0008A



# PACKAGE OUTLINE

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4214862/A 04/2023

**NOTES:**

PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

# EXAMPLE BOARD LAYOUT

DGK0008A

™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

# EXAMPLE STENCIL DESIGN

DGK0008A

<sup>TM</sup> VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.



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